

# Dual Supply Octal Translating Transceiver

with 3-State Outputs

## MC74LVX4245

The 74LVX4245 is a 24-pin dual-supply, octal translating transceiver that is designed to interface between a 5.0 V bus and a 3.0 V bus in a mixed 3.0 V / 5.0 V supply environment such as laptop computers using a 3.3 V CPU and 5.0 V LCD display. The A port interfaces with the 5V bus; the B port interfaces with the 3.0 V bus.

The Transmit/Receive ( $\overline{T/R}$ ) input determines the direction of data flow. Transmit (active-High) enables data from the A port to the B port. Receive (active-Low) enables data from the B port to the A port. The Output Enable ( $\overline{OE}$ ) input, when High, disables both A and B ports by placing them in 3-State.

### Features

- Bi-directional Interface Between 5.0 V and 3.0 V Buses
- Control Inputs Compatible with TTL Level
- 5.0 V Data Flow at A Port and 3.0 V Data Flow at B Port
- Outputs Source/Sink 24 mA at 5.0 V Bus and 12 mA at 3.0 V Bus
- Guaranteed Simultaneous Switching Noise Level and Dynamic Threshold Performance
- Available in SOIC and TSSOP Packages
- Functionally Compatible with the 74 Series 245
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

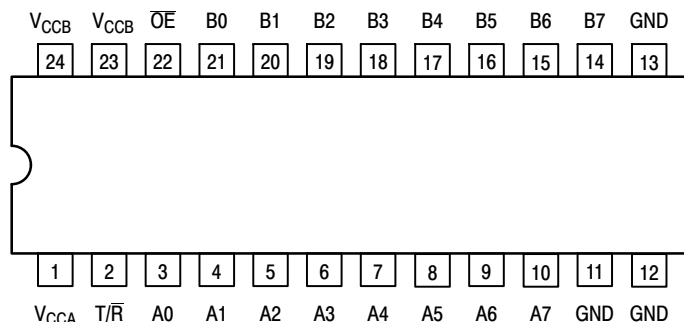
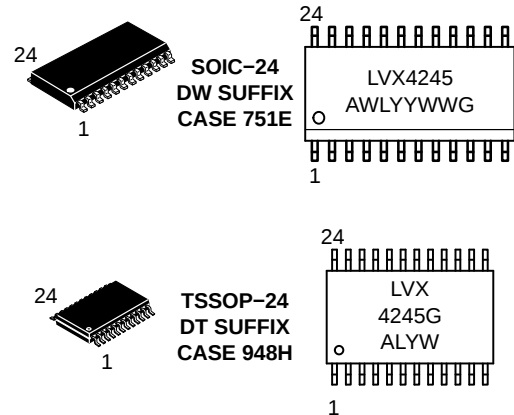


Figure 1. 24-Lead Pinout  
(Top View)

### MARKING DIAGRAMS



LVX4245 = Specific Device Code  
A = Assembly Location  
WL, L = Wafer Lot  
Y = Year  
WW, W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

### PIN NAMES

| Pins             | Function                                 |
|------------------|------------------------------------------|
| $\overline{OE}$  | Output Enable Input                      |
| $\overline{T/R}$ | Transmit/Receive Input                   |
| A0–A7            | Side A 3-State Inputs or 3-State Outputs |
| B0–B7            | Side B 3-State Inputs or 3-State Outputs |

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 5.

# MC74LVX4245

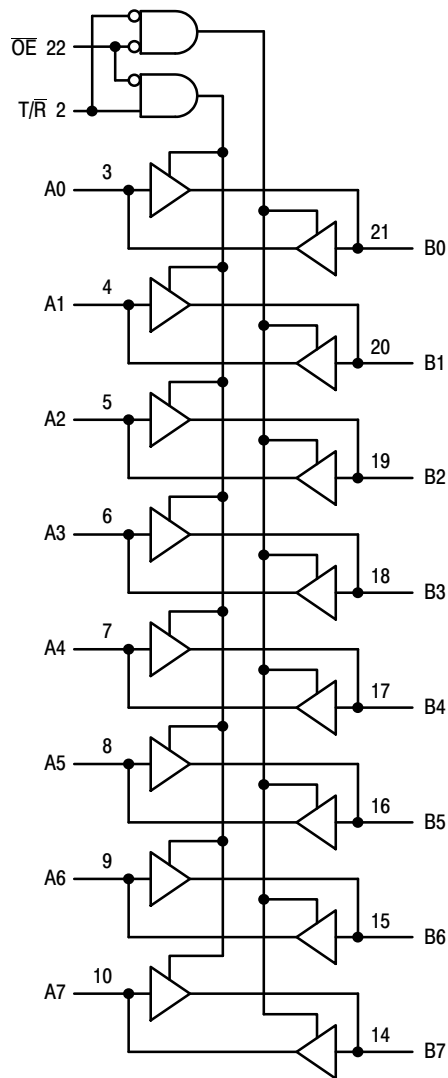


Figure 2. Logic Diagram

| INPUTS |     | OPERATING MODE<br>Non-Inverting |
|--------|-----|---------------------------------|
| OE     | T/R |                                 |
| L      | L   | B Data to A Bus                 |
| L      | H   | A Data to B Bus                 |
| H      | X   | Z                               |

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions are Acceptable; For I<sub>CC</sub> reasons, Do Not Float Inputs

# MC74LVX4245

## ABSOLUTE MAXIMUM RATINGS

| Symbol             | Parameter                                                                                           | Value                              | Condition                 | Unit |
|--------------------|-----------------------------------------------------------------------------------------------------|------------------------------------|---------------------------|------|
| $V_{CCA}, V_{CCB}$ | DC Supply Voltage                                                                                   | -0.5 to +7.0                       |                           | V    |
| $V_I$              | DC Input Voltage $\overline{OE}, T/\overline{R}$                                                    | -0.5 to $V_{CCA} + 0.5$            |                           | V    |
| $V_{I/O}$          | DC Input/Output Voltage                                                                             | An                                 | -0.5 to $V_{CCA} + 0.5$   | V    |
|                    |                                                                                                     | Bn                                 | -0.5 to $V_{CCB} + 0.5$   | V    |
| $I_{IK}$           | DC Input Diode Current $\overline{OE}, T/\overline{R}$                                              | $\pm 20$                           | $V_I < GND$               | mA   |
| $I_{OK}$           | DC Output Diode Current                                                                             | $\pm 50$                           | $V_O < GND; V_O > V_{CC}$ | mA   |
| $I_O$              | DC Output Source/Sink Current                                                                       | $\pm 50$                           |                           | mA   |
| $I_{CC}, I_{GND}$  | DC Supply Current<br>Per Output Pin<br>Maximum Current at $I_{CCA}$<br>Maximum Current at $I_{CCB}$ | $\pm 50$<br>$\pm 200$<br>$\pm 100$ |                           | mA   |
| $T_{STG}$          | Storage Temperature Range                                                                           | -65 to +150                        |                           | °C   |
| Latchup            | DC Latchup Source/Sink Current                                                                      | $\pm 300$                          |                           | mA   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## RECOMMENDED OPERATING CONDITIONS

| Symbol              | Parameter                                                                                      | Min        | Max                | Unit |
|---------------------|------------------------------------------------------------------------------------------------|------------|--------------------|------|
| $V_{CCA}, V_{CCB}$  | Supply Voltage $V_{CCA}, V_{CCB}$                                                              | 4.5<br>2.7 | 5.5<br>3.6         | V    |
| $V_I$               | Input Voltage $\overline{OE}, T/\overline{R}$                                                  | 0          | $V_{CCA}$          | V    |
| $V_{I/O}$           | Input/Output Voltage<br>An<br>Bn                                                               | 0<br>0     | $V_{CCA}, V_{CCB}$ | V    |
| $T_A$               | Operating Free-Air Temperature                                                                 | -40        | +85                | °C   |
| $\Delta t/\Delta V$ | Minimum Input Edge Rate<br>$V_{IN}$ from 30% to 70% of $V_{CC}$ ; $V_{CC}$ at 3.0V, 4.5V, 5.5V | 0          | 8                  | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

| Symbol           | Parameter                         |                         | Condition                                                                      | V <sub>CCA</sub>  | V <sub>CCB</sub>  | T <sub>A</sub> = 25°C |                      | T <sub>A</sub> = -40 to +85°C |            | Unit |
|------------------|-----------------------------------|-------------------------|--------------------------------------------------------------------------------|-------------------|-------------------|-----------------------|----------------------|-------------------------------|------------|------|
|                  |                                   |                         |                                                                                |                   |                   | Typ                   | Guaranteed Limits    |                               |            |      |
| V <sub>IHA</sub> | Minimum HIGH Level Input Voltage  | An, $\overline{OE}$ T/R | V <sub>OUT</sub> ≤ 0.1V or<br>≥ V <sub>CC</sub> - 0.1V                         | 5.5<br>4.5        | 3.3<br>3.3        |                       | 2.0<br>2.0           | 2.0<br>2.0                    | V          |      |
| V <sub>IHB</sub> |                                   | Bn                      |                                                                                |                   | 5.0<br>5.0        | 3.6<br>2.7            |                      | 2.0<br>2.0                    | 2.0<br>2.0 | V    |
| V <sub>ILA</sub> | Maximum LOW Level Input Voltage   | An, $\overline{OE}$ T/R | V <sub>OUT</sub> ≤ 0.1V or<br>≥ V <sub>CC</sub> - 0.1V                         | 5.5<br>4.5        | 3.3<br>3.3        |                       | 0.8<br>0.8           | 0.8<br>0.8                    | V          |      |
| V <sub>ILB</sub> |                                   | Bn                      |                                                                                |                   | 5.0<br>5.0        | 2.7<br>3.6            |                      | 0.8<br>0.8                    | 0.8<br>0.8 | V    |
| V <sub>OHA</sub> | Minimum HIGH Level Output Voltage |                         | I <sub>OUT</sub> = -100μA<br>I <sub>OH</sub> = -24mA                           | 4.5<br>4.5        | 3.0<br>3.0        | 4.50<br>4.25          | 4.40<br>3.86         | 4.40<br>3.76                  | V          |      |
| V <sub>OHB</sub> |                                   |                         | I <sub>OUT</sub> = -100μA<br>I <sub>OH</sub> = -12mA<br>I <sub>OH</sub> = -8mA | 4.5<br>4.5<br>4.5 | 3.0<br>3.0<br>2.7 | 2.99<br>2.80<br>2.50  | 2.9<br>2.4<br>2.4    | 2.9<br>2.4<br>2.4             | V          |      |
|                  |                                   |                         |                                                                                |                   |                   |                       |                      |                               |            |      |
| V <sub>OLA</sub> | Maximum LOW Level Output Voltage  |                         | I <sub>OUT</sub> = 100μA<br>I <sub>OL</sub> = 24mA                             | 4.5<br>4.5        | 3.0<br>3.0        | 0.002<br>0.18         | 0.10<br>0.36         | 0.10<br>0.44                  | V          |      |
| V <sub>OLB</sub> |                                   |                         | I <sub>OUT</sub> = 100μA<br>I <sub>OL</sub> = 12mA<br>I <sub>OL</sub> = 8mA    | 4.5<br>4.5<br>4.5 | 3.0<br>3.0<br>2.7 | 0.002<br>0.1<br>0.1   | 0.10<br>0.31<br>0.31 | 0.10<br>0.40<br>0.40          | V          |      |
|                  |                                   |                         |                                                                                |                   |                   |                       |                      |                               |            |      |

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## DC ELECTRICAL CHARACTERISTICS

| Symbol                                 | Parameter                                 |                            | Condition                                                                                                                           | V <sub>CCA</sub> | V <sub>CCB</sub> | T <sub>A</sub> = 25°C |                   | T <sub>A</sub> = −40 to +85°C | Unit |
|----------------------------------------|-------------------------------------------|----------------------------|-------------------------------------------------------------------------------------------------------------------------------------|------------------|------------------|-----------------------|-------------------|-------------------------------|------|
|                                        |                                           |                            |                                                                                                                                     |                  |                  | Typ                   | Guaranteed Limits |                               |      |
| I <sub>IN</sub>                        | Max Input Leak-age Current                | $\overline{OE}$ ,<br>T/R   | V <sub>I</sub> = V <sub>CCA</sub> , GND                                                                                             | 5.5              | 3.6              |                       | ±0.1              | ±1.0                          | μA   |
| I <sub>OZA</sub>                       | Max 3-State Out-put Leakage               | An                         | V <sub>I</sub> = V <sub>IH</sub> , V <sub>IL</sub><br>$\overline{OE}$ = V <sub>CCA</sub><br>V <sub>O</sub> = V <sub>CCA</sub> , GND | 5.5              | 3.6              |                       | ±0.5              | ±5.0                          | μA   |
| I <sub>OZB</sub>                       | Max 3-State Out-put Leakage               | Bn                         | V <sub>I</sub> = V <sub>IH</sub> , V <sub>IL</sub><br>$\overline{OE}$ = V <sub>CCA</sub><br>V <sub>O</sub> = V <sub>CCB</sub> , GND | 5.5              | 3.6              |                       | ±0.5              | ±5.0                          | μA   |
| ΔI <sub>CC</sub>                       | Maximum I <sub>CCT</sub> per Input        | An, $\overline{OE}$<br>T/R | V <sub>I</sub> =V <sub>CCA</sub> −2.1V                                                                                              | 5.5              | 3.6              | 1.0                   | 1.35              | 1.5                           | mA   |
|                                        |                                           | Bn                         | V <sub>I</sub> =V <sub>CCB</sub> −0.6V                                                                                              | 5.5              | 3.6              |                       | 0.35              | 0.5                           | mA   |
| I <sub>CCA</sub>                       | Quiescent V <sub>CCA</sub> Supply Current |                            | An=V <sub>CCA</sub> or GND<br>Bn=V <sub>CCB</sub> or GND<br>$\overline{OE}$ =GND<br>T/R=GND                                         | 5.5              | 3.6              |                       | 8                 | 80                            | μA   |
| I <sub>CCB</sub>                       | Quiescent V <sub>CCB</sub> Supply Current |                            | An=V <sub>CCA</sub> or GND<br>Bn=V <sub>CCB</sub> or GND<br>$\overline{OE}$ =GND<br>T/R=V <sub>CCA</sub>                            | 5.5              | 3.6              |                       | 5                 | 50                            | μA   |
| V <sub>OLPA</sub><br>V <sub>OLPB</sub> | Quiet Output Max Dynamic V <sub>OL</sub>  |                            | Notes 1, 2                                                                                                                          | 5.0<br>5.0       | 3.3<br>3.3       |                       | 1.5<br>1.2        |                               | V    |
| V <sub>OLVA</sub><br>V <sub>OLVB</sub> | Quiet Output Min Dynamic V <sub>OL</sub>  |                            | Notes 1, 2                                                                                                                          | 5.0<br>5.0       | 3.3<br>3.3       |                       | −1.2<br>−0.8      |                               | V    |
| V <sub>IHDA</sub><br>V <sub>IHDB</sub> | Min HIGH Level Dynamic Input Voltage      |                            | Notes 1, 3                                                                                                                          | 5.0<br>5.0       | 3.3<br>3.3       |                       | 2.0<br>2.0        |                               | V    |
| V <sub>ILDA</sub><br>V <sub>ILDB</sub> | Max LOW Level Dynamic Input Voltage       |                            | Notes 1, 3                                                                                                                          | 5.0<br>5.0       | 3.3<br>3.3       |                       | 0.8<br>0.8        |                               | V    |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Worst case package.
2. Max number of outputs defined as (n). Data inputs are driven 0V to V<sub>CC</sub> level; one output at GND.
3. Max number of data inputs (n) switching. (n-1) inputs switching 0V to V<sub>CC</sub> level. Input under test switching: V<sub>CC</sub> level to threshold (V<sub>IHD</sub>), 0V to threshold (V<sub>ILD</sub>), f = 1MHz.

## CAPACITIVE CHARACTERISTICS

| Symbol           | Parameter                                            | Condition                                        | Typical | Unit |
|------------------|------------------------------------------------------|--------------------------------------------------|---------|------|
| C <sub>IN</sub>  | Input Capacitance                                    | V <sub>CCA</sub> = 5.0V; V <sub>CCB</sub> = 3.3V | 4.5     | pF   |
| C <sub>I/O</sub> | Input/Output Capacitance                             | V <sub>CCA</sub> = 5.0V; V <sub>CCB</sub> = 3.3V | 15      | pF   |
| C <sub>PD</sub>  | Power Dissipation Capacitance<br>(Measured at 10MHz) | B→A                                              | 55      | pF   |
|                  |                                                      | A→B                                              | 40      |      |

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## AC ELECTRICAL CHARACTERISTICS

| Symbol                                 | Parameter                                      | T <sub>A</sub> = −40 to +85°C<br>C <sub>L</sub> = 50pF       |                 |              | T <sub>A</sub> = −40 to +85°C<br>C <sub>L</sub> = 50pF |              | Unit |
|----------------------------------------|------------------------------------------------|--------------------------------------------------------------|-----------------|--------------|--------------------------------------------------------|--------------|------|
|                                        |                                                | V <sub>CCA</sub> = 5V ±0.5V<br>V <sub>CCB</sub> = 3.3V ±0.3V |                 |              | V <sub>CCA</sub> = 5V ±0.5V<br>V <sub>CCB</sub> = 2.7V |              |      |
|                                        |                                                | Min                                                          | Typ<br>(Note 4) | Max          | Min                                                    | Max          |      |
| t <sub>PHL</sub><br>t <sub>PLH</sub>   | Propagation Delay A to B                       | 1.0<br>1.0                                                   | 5.1<br>5.3      | 9.0<br>9.0   | 1.0<br>1.0                                             | 10.0<br>10.0 | ns   |
| t <sub>PHL</sub><br>t <sub>PLH</sub>   | Propagation Delay B to A                       | 1.0<br>1.0                                                   | 5.4<br>5.5      | 9.0<br>9.0   | 1.0<br>1.0                                             | 10.0<br>10.0 | ns   |
| t <sub>PZL</sub><br>t <sub>PZH</sub>   | Output Enable Time $\overline{OE}$ to B        | 1.0<br>1.0                                                   | 6.5<br>6.7      | 10.5<br>10.5 | 1.0<br>1.0                                             | 11.5<br>11.5 | ns   |
| t <sub>PZL</sub><br>t <sub>PZH</sub>   | Output Enable Time $\overline{OE}$ to A        | 1.0<br>1.0                                                   | 5.2<br>5.8      | 9.5<br>9.5   | 1.0<br>1.0                                             | 10.0<br>10.0 | ns   |
| t <sub>PHZ</sub><br>t <sub>PLZ</sub>   | Output Disable Time $\overline{OE}$ to B       | 1.0<br>1.0                                                   | 6.0<br>3.3      | 10.0<br>7.0  | 1.0<br>1.0                                             | 10.0<br>7.5  | ns   |
| t <sub>PHZ</sub><br>t <sub>PLZ</sub>   | Output Disable Time $\overline{OE}$ to A       | 1.0<br>1.0                                                   | 3.9<br>2.9      | 7.5<br>7.0   | 1.0<br>1.0                                             | 7.5<br>7.5   | ns   |
| t <sub>OSHL</sub><br>t <sub>OSLH</sub> | Output to Output Skew, Data to Output (Note 5) |                                                              | 1.0             | 1.5          |                                                        | 1.5          | ns   |

4. Typical values at V<sub>CCA</sub> = 5.0V; V<sub>CCB</sub> = 3.3V at 25°C.

5. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

## ORDERING INFORMATION

| Device           | Package               | Shipping†          |
|------------------|-----------------------|--------------------|
| MC74LVX4245DWR2G | SOIC-24<br>(Pb-Free)  | 1000 / Tape & Reel |
| MC74LVX4245DTR2G | TSSOP-24<br>(Pb-Free) | 2500 / Tape & Reel |

## DISCONTINUED (Note 6)

|                  |                       |                    |
|------------------|-----------------------|--------------------|
| MC74LVX4245DWG   | SOIC-24<br>(Pb-Free)  | 30 Units / Rail    |
| MC74LVX4245DTG   | TSSOP-24<br>(Pb-Free) | 62 Units / Rail    |
| NLVLVX4245DTR2G* |                       | 2500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

6. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on [www.onsemi.com](http://www.onsemi.com).

### Dual Supply Octal Translating Transceiver

The 74LVX4245 is a dual-supply device well capable of bidirectional signal voltage translation. This level shifting ability provides an excellent interface between low voltage CPU local bus and a standard 5.0 V I/O bus. The device control inputs can be controlled by either the low voltage CPU and core logic or a bus arbitrator with 5.0 V I/O levels.

The LVX4245 is ideal for mixed voltage applications such as notebook computers using a 3.3 V CPU and 5.0 V peripheral devices.

### Applications:

#### Mixed Mode Dual Supply Interface Solutions

The LVX4245 is designed to solve 3.0 V / 5.0 V interfaces when CMOS devices cannot tolerate I/O levels above their applied  $V_{CC}$ . If an I/O pin of a 3.0 V device is driven by a 5.0 V device, the P-Channel transistor in the 3.0 V device will conduct – causing current flow from the I/O bus to the 3.0 V power supply. The result may be destruction of the 3.0 V device through latchup effects. A current limiting resistor may be used to prevent destruction, but it causes speed degradation and needless power dissipation.

A better solution is provided in the LVX4245. It provides two different output levels that easily handle the dual voltage interface. The A port is a dedicated 5.0 V port; the B port is a dedicated 3.0 V port.

Since the LVX4245 is a '245 transceiver, the user may either use it for bidirectional or unidirectional applications. The center 20 pins are configured to match a '245 pinout. This enables the user to easily replace this level shifter with a 3.0 V '245 device without additional layout work or re-manufacture of the circuit board (when both buses are 3.0 V).

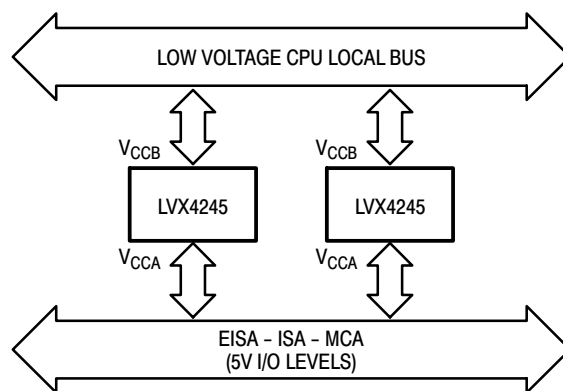


Figure 3. 3.3V/5V Interface Block Diagram

### Powering Up the LVX4245

When powering up the LVX4245, please note that if the  $V_{CCB}$  pin is powered-up well in advance of the  $V_{CCA}$  pin, several milliamps of either  $I_{CCA}$  or  $I_{CCB}$  current will result. If the  $V_{CCA}$  pin is powered-up in advance of the  $V_{CCB}$  pin then only nanoamps of  $I_{CC}$  current will result. In actuality the  $V_{CCB}$  can be powered “slightly” before the  $V_{CCA}$  without the current penalty, but this “setup time” is dependent on the power-up ramp rate of the  $V_{CC}$  pins. With a ramp rate of approximately 50 mV/ns (50V/ $\mu$ s) a 25 ns setup time was observed ( $V_{CCB}$  before  $V_{CCA}$ ). With a 7.0 V/ $\mu$ s rate, the setup time was about 140ns. When all is said and done, the safest powerup strategy is to simply power  $V_{CCA}$  before  $V_{CCB}$ . One more note: if the  $V_{CCB}$  ramp rate is faster than the  $V_{CCA}$  ramp rate then power problems might still occur, even if the  $V_{CCA}$  powerup began prior to the  $V_{CCB}$  powerup.

## MC74LVX4245

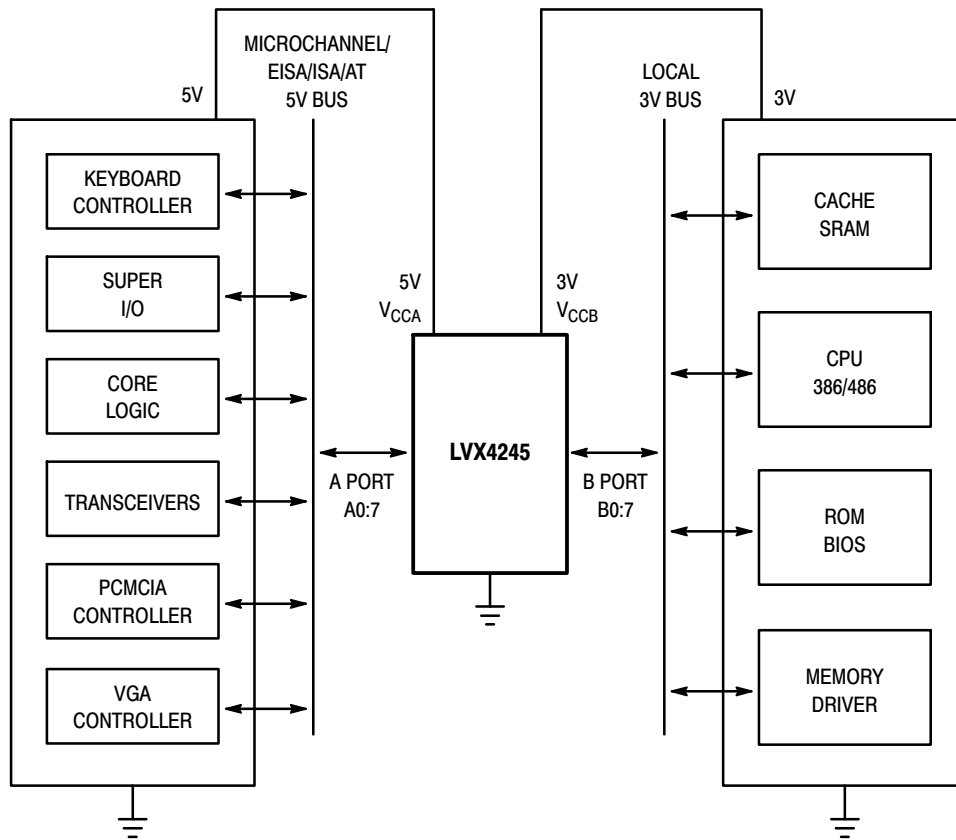


Figure 4. MC74LVX4245 Fits Into a System with 3V Subsystem and 5V Subsystem

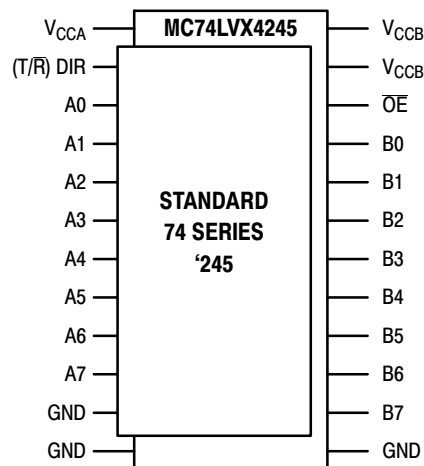
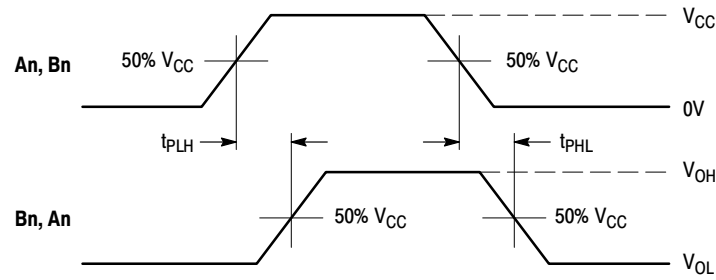


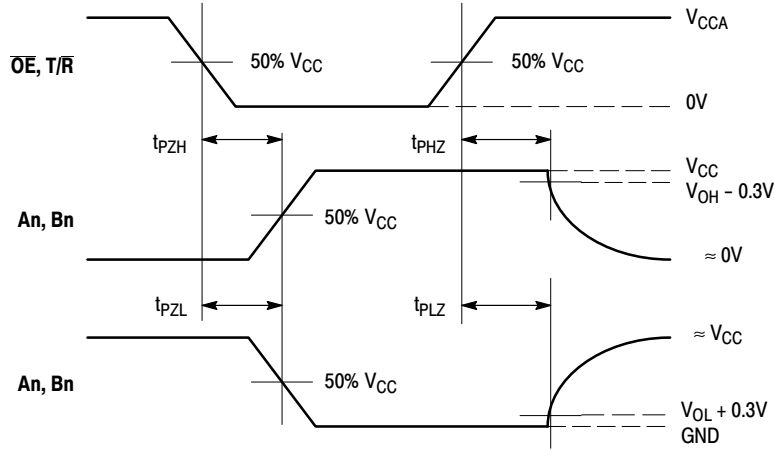
Figure 5. MC74LVX4245 Pin Arrangement Is Compatible to 20-Pin 74 Series '245s

## MC74LVX4245



**WAVEFORM 1 - PROPAGATION DELAYS**

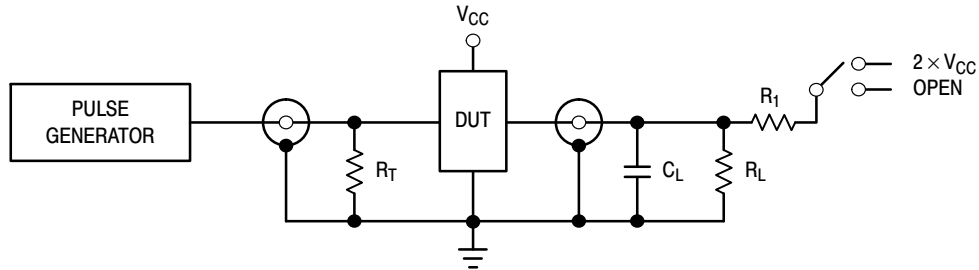
$t_R = t_F = 2.5\text{ns}$ , 10% to 90%;  $f = 1\text{MHz}$ ;  $t_W = 500\text{ns}$



**WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES**

$t_R = t_F = 2.5\text{ns}$ , 10% to 90%;  $f = 1\text{MHz}$ ;  $t_W = 500\text{ns}$

**Figure 6. AC Waveforms**



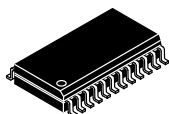
| TEST                                          | SWITCH            |
|-----------------------------------------------|-------------------|
| $t_{PLH}$ , $t_{PHL}$ , $t_{PZH}$ , $t_{PHZ}$ | Open              |
| $t_{PZL}$ , $t_{PLZ}$                         | $2 \times V_{CC}$ |

$C_L = 50\text{pF}$  or equivalent (Includes jig and probe capacitance)

$R_L = R_1 = 500\Omega$  or equivalent

$R_T = Z_{OUT}$  of pulse generator (typically  $50\Omega$ )

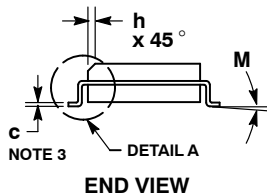
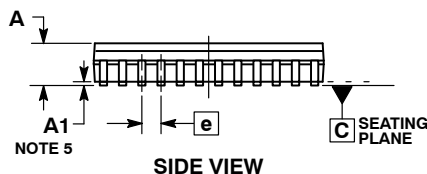
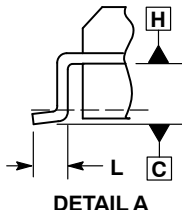
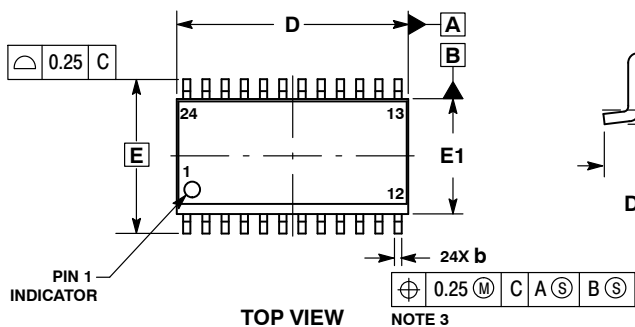
**Figure 7. Test Circuit**



SCALE 1:1

SOIC-24 WB  
CASE 751E-04  
ISSUE F

DATE 03 JUL 2012

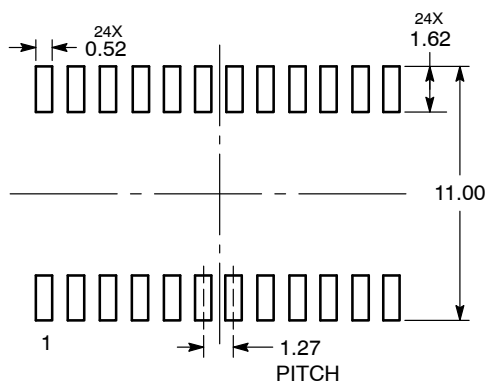


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b and c APPLY TO THE FLAT SECTION OF THE LEAD AND ARE MEASURED BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

| MILLIMETERS |           |       |
|-------------|-----------|-------|
| DIM         | MIN       | MAX   |
| A           | 2.35      | 2.65  |
| A1          | 0.13      | 0.29  |
| b           | 0.35      | 0.49  |
| c           | 0.23      | 0.32  |
| D           | 15.25     | 15.54 |
| E           | 10.30 BSC |       |
| E1          | 7.40      | 7.60  |
| e           | 1.27 BSC  |       |
| h           | 0.25      | 0.75  |
| L           | 0.41      | 0.90  |
| M           | 0°        | 8°    |

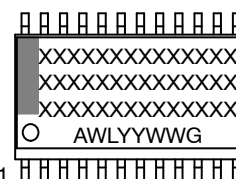
RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*

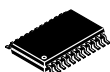


XXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

|                  |             |                                                                                                                                                                                     |
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| DESCRIPTION:     | SOIC-24 WB  | PAGE 1 OF 1                                                                                                                                                                         |

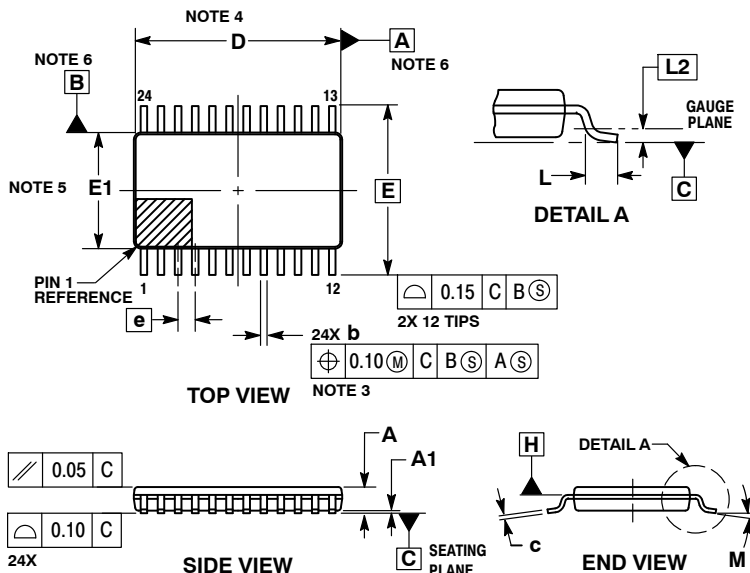
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SCALE 1:1

TSSOP24 7.8x4.4, 0.65P  
CASE 948H  
ISSUE B

DATE 21 JUN 2012

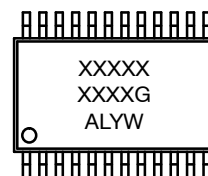


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION D IS DETERMINED AT DATUM PLANE H.
5. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE. DIMENSION E1 IS DETERMINED AT DATUM PLANE H.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | ---         | 1.20 |
| A1  | 0.05        | 0.15 |
| b   | 0.19        | 0.30 |
| c   | 0.09        | 0.20 |
| D   | 7.70        | 7.90 |
| E   | 6.40 BSC    |      |
| E1  | 4.30        | 4.50 |
| e   | 0.65 BSC    |      |
| L   | 0.50        | 0.75 |
| L2  | 0.25 BSC    |      |
| M   | 0°          | 8°   |

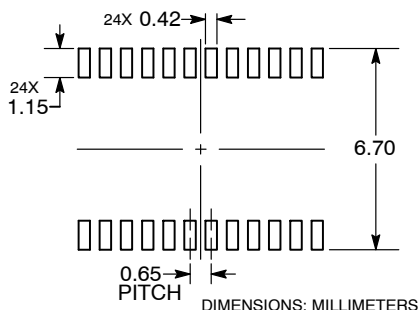
GENERIC  
MARKING DIAGRAM\*



XXXX = Specific Device Code  
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\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                  |                        |                                                                                                                                                                                  |
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| DESCRIPTION:     | TSSOP24 7.8X4.4, 0.65P | PAGE 1 OF 1                                                                                                                                                                      |

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